## **DECLARATION - USA PATENT APPLICATION**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled MECHANISM FOR EXCHANGING CHIP-CARRIER PLATES FOR USE IN A HYBRID CHIP-BONDING MACHINE; the specification of which was filed on February 21, 2002 as Application Serial No. 10/081,028.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56;

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

## PRIOR FOREIGN APPLICATION(S)

Priority Claimed

No.: 01126708.5

Country: Europe

Date Filed: November 8, 2001

Yes

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.

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Full name of sole inventor: Dr. Farhad Farassat

Inventor's signature

te ADril 17, 2007

Residence: Veilchenweg 91, D-82024 Taufkirchen, Germany

Citizenship: German

Post Office Address: Veilchenweg 91, D-82024 Taufkirchen, Germany

Send Correspondence To: KNOBBE, MARTENS, OLSON & BEAR, LLP Customer No. 20,995

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MEIS	568 001 AUS			PATENT
MAY 1	IN THE UNITED STATES PATENT AND TRADEMAR			DEMARK OFFICE
VZ/	A pricant	:	Dr. Farhad Farassat	)
	App. No.	:	10/081,028	COPY OF PAPERS ORIGINALLY FILED
	Filed	: .	February 21, 2002	)
	For	:	MECHANISM FOR EXCHANGING CHIP-CARRIER PLATES FOR USE IN A HYBRID CHIP-BONDING MACHINE	) ) ) )
	Examiner	:	Unknown	) )

## ESTABLISHMENT OF RIGHT OF ASSIGNEE TO TAKE ACTION AND REVOCATION AND POWER OF ATTORNEY

United States Patent and Trademark Office P.O. Box 2327 Arlington, VA 22202

## Dear Sir:

The undersigned is empowered to act on behalf of the assignee below (the "Assignee"). A true copy of the original Assignment of the above-captioned application from the inventor(s) to the Assignee is attached hereto. This Assignment represents the entire chain of title of this invention from the Inventor(s) to the Assignee.

I declare that all statements made herein are true, and that all statements made upon information and belief are believed to be true, and further, that these statements were made with the knowledge that willful, false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001, and that willful, false statements may jeopardize the validity of the application, or any patent issuing thereon.

The undersigned hereby revokes any previous powers of attorney in the subject application, and hereby appoints the registrants of Knobbe, Martens, Olson & Bear, LLP, 620

App. No.

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:

February 21, 2002

Newport Center Drive, Sixteenth Floor, Newport Beach, California 92660, Telephone (949) 760-0404, Customer No. 20,995, as its attorneys with full power of substitution and revocation to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected herewith. This appointment is to be to the exclusion of the inventor(s) and his attorney(s) in accordance with the provisions of 37 C.F.R. § 3.71.

Please use Customer No. 20,995 for all communications.

F & K Delvotec Bondtechnik GmbH

Dated: APril 17 2002

By: Flatalla

Title:

Address: Daimlerstrasse 5

D-85521 Ottobrunn

Germany

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**PATENT** 

Client Code: MEISS68.001AUS

Page 1

Application No.: 10/081,028 Filing Date: February 21, 2002

COPA

HEREAS FOR LET Farhad Paragraf, a German citizen, residing at Veilchenweg 91, D-82024 Taufkirchen, have inverted certain new and useful improvements in a MECHANISM FOR EXCHANGING CHIP-CARRIER PLATES FOR USE IN A HYBRID CHIP-BONDING MACHINE for which I have filed an application for Letters Patent in the United States, Application No. 10/081,028, filed February 21, 2002;

AND WHEREAS, F & K Delvotec Bondtechnick GmbH (hereinafter "ASSIGNEE"), with its principal place of business at Daimlerstrasse 5, D-85521 Ottobrunn, Germany, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said inventor, do hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications of vetters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

IN TESTIMONY WHEREOF, I hereunto se

day of APTI, 2007

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